
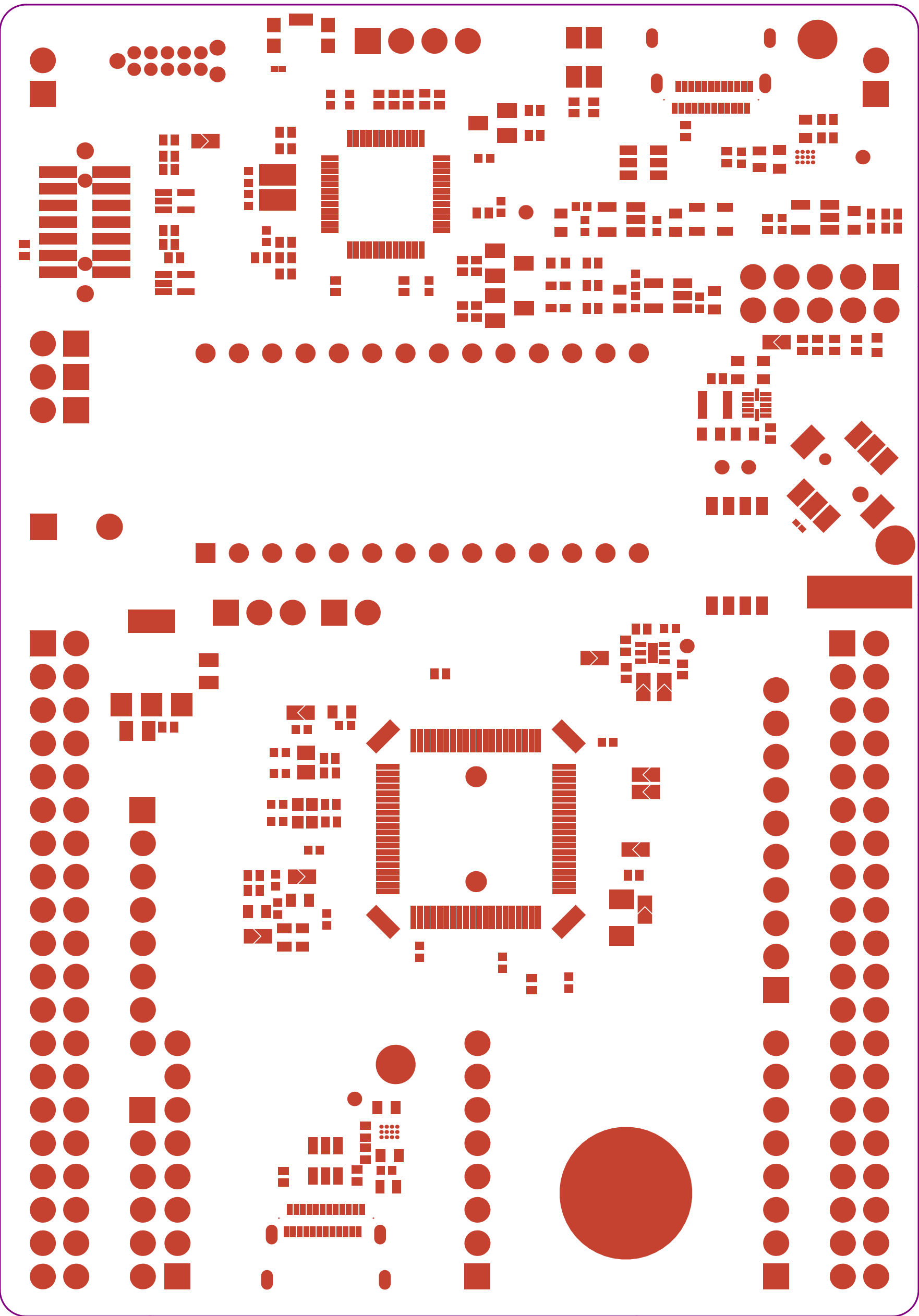

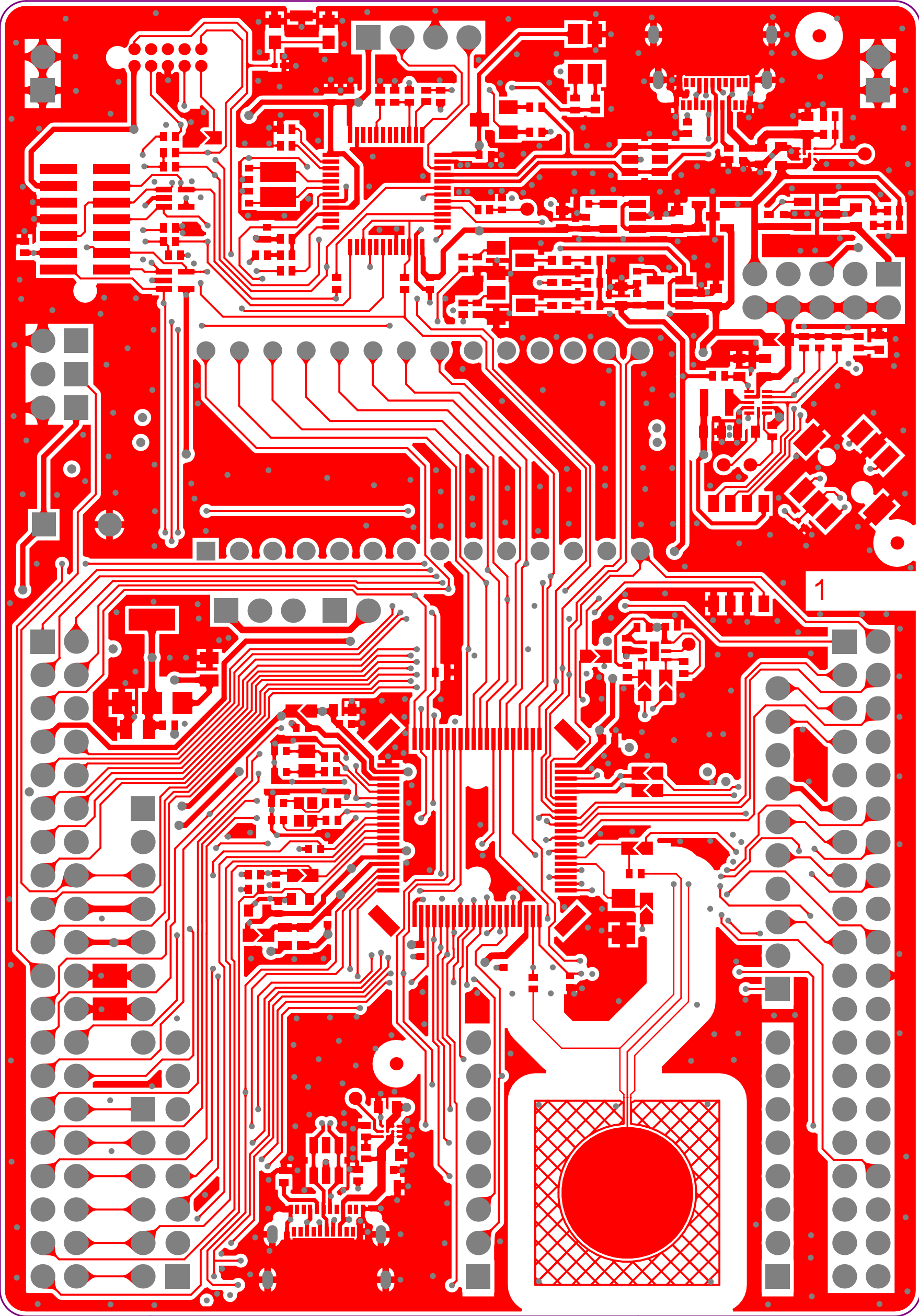



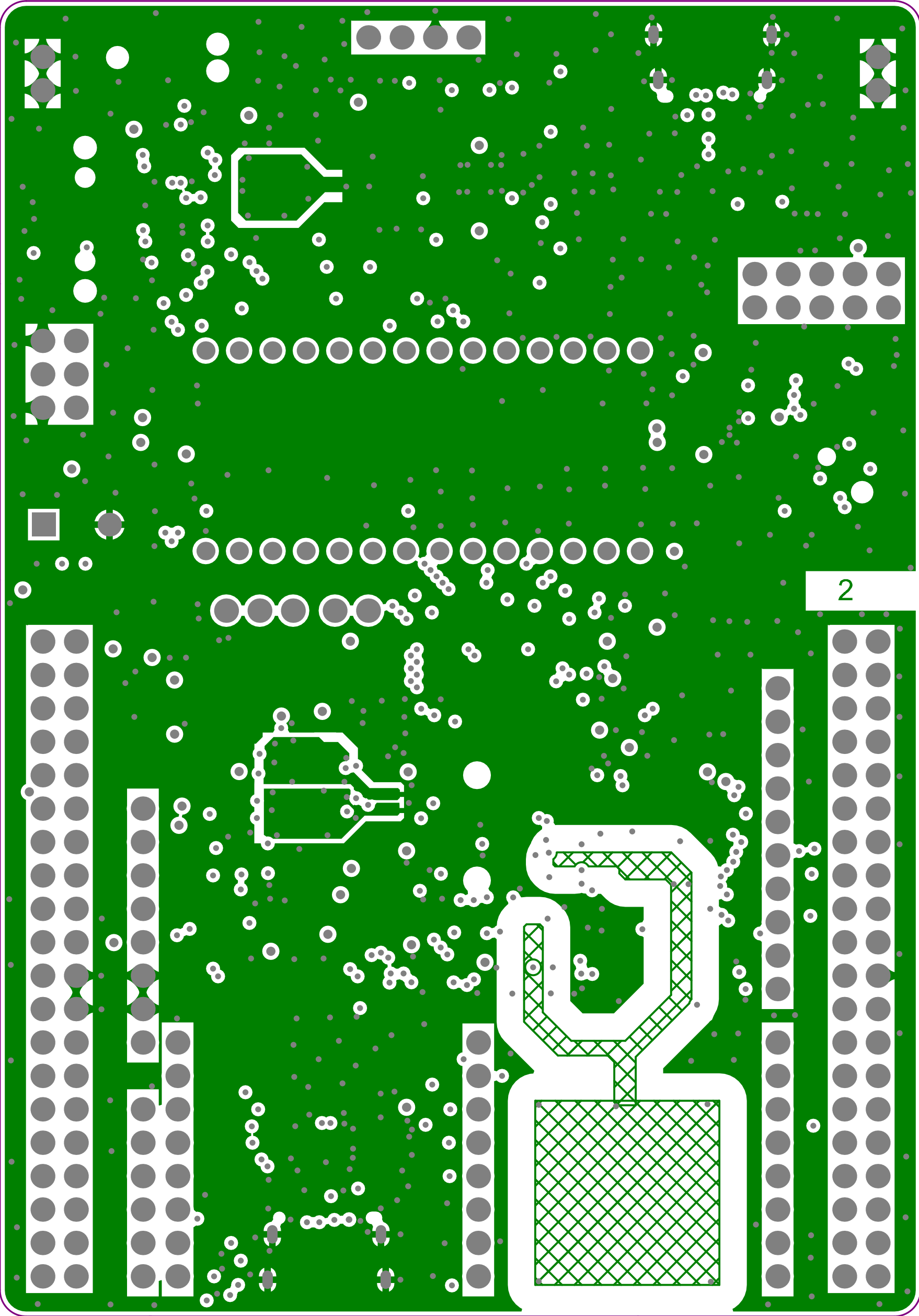
Project: STM32U083C-DK		
Layer: Top Overlay	Gerber: .GTO	
Variant: U083C	Ref: MB1933	
Date: 26-SEP-2023	Rev: C	




Project: STM32U083C-DK		
Layer: <b>Top Solder</b>	Gerber: <b>.GTS</b>	
Variant: U083C	Ref: MB1933	
Date: 26-SEP-2023	Rev: C	

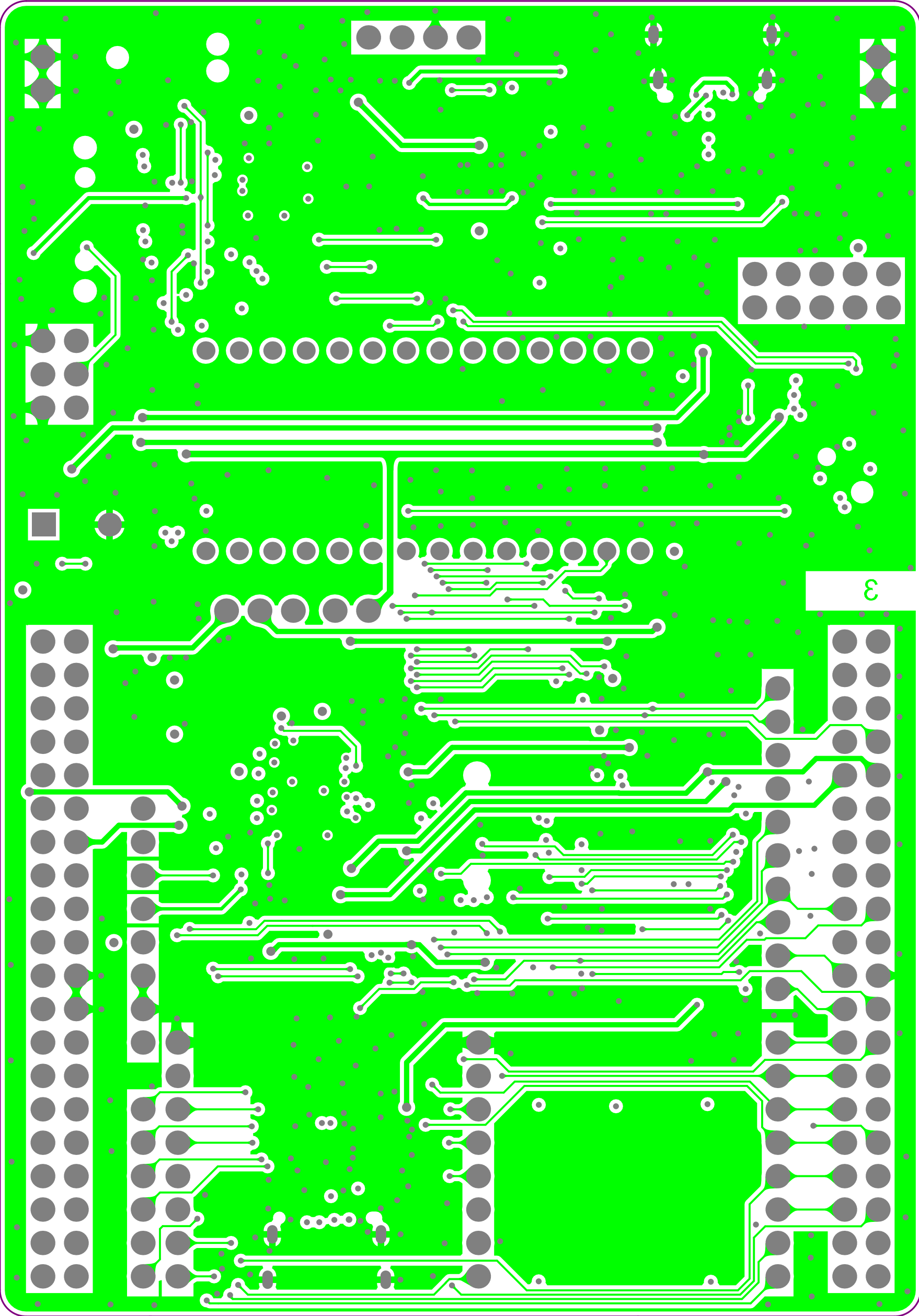



Project: STM32U083C-DK		
Layer: <b>Top Layer</b>	Gerber: <b>.GTL</b>	
Variant: U083C	Ref: MB1933	
Date: 26-SEP-2023	Rev: C	

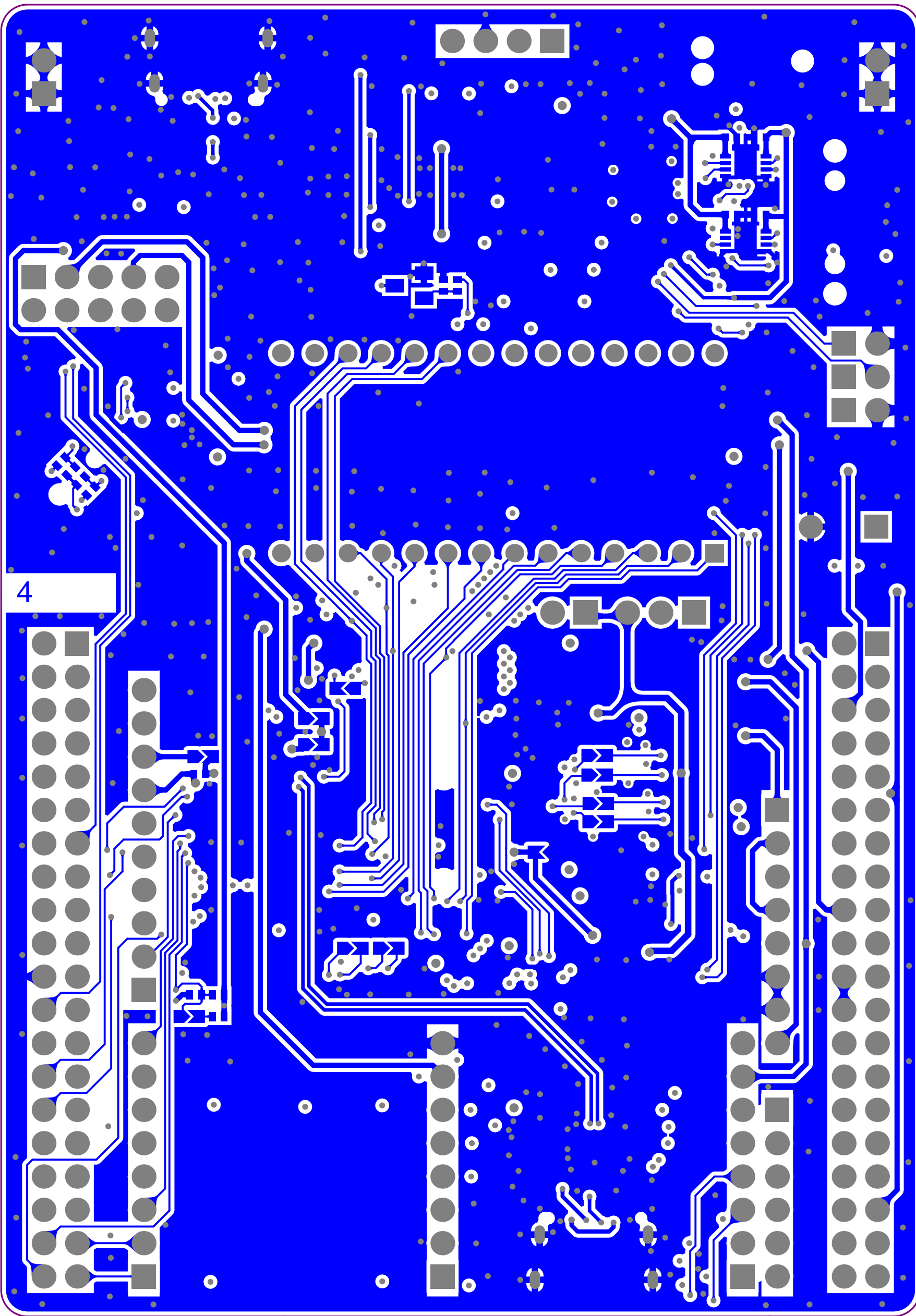


Project: STM32U083C-DK		
Layer: M1 Layer	Gerber: .G1	
Variant: U083C	Ref: MB1933	
Date: 26-SEP-2023	Rev: C	





Project: STM32U083C-DK		
Layer: M2 Layer	Gerber: .G2	
Variant: U083C	Ref: MB1933	
Date: 26-SEP-2023	Rev: C	



Project: STM32U083C-DK

Layer: Bottom Layer

Variant: U083C

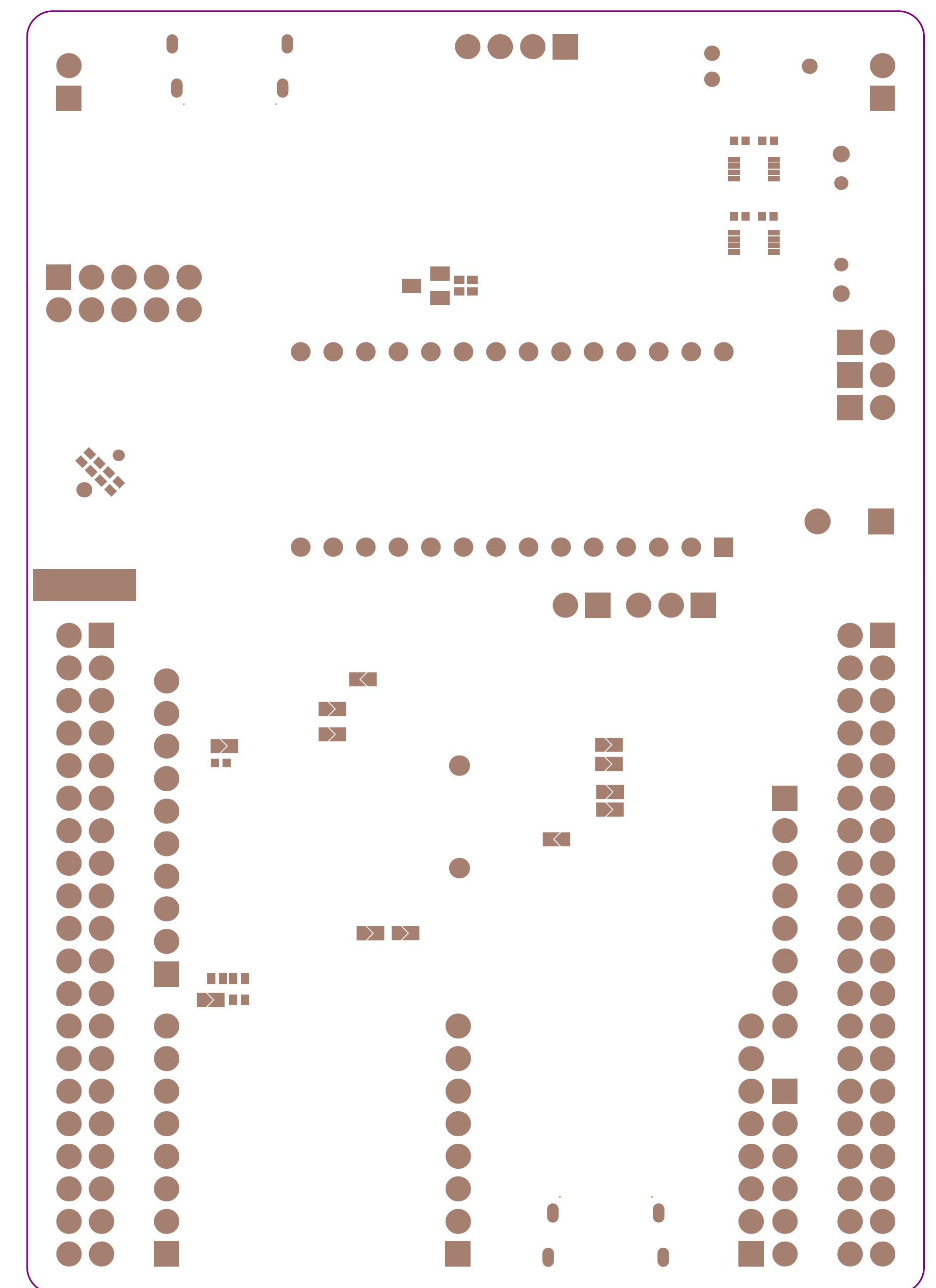
Date: 26-SEP-2023


Gerber: .GBL

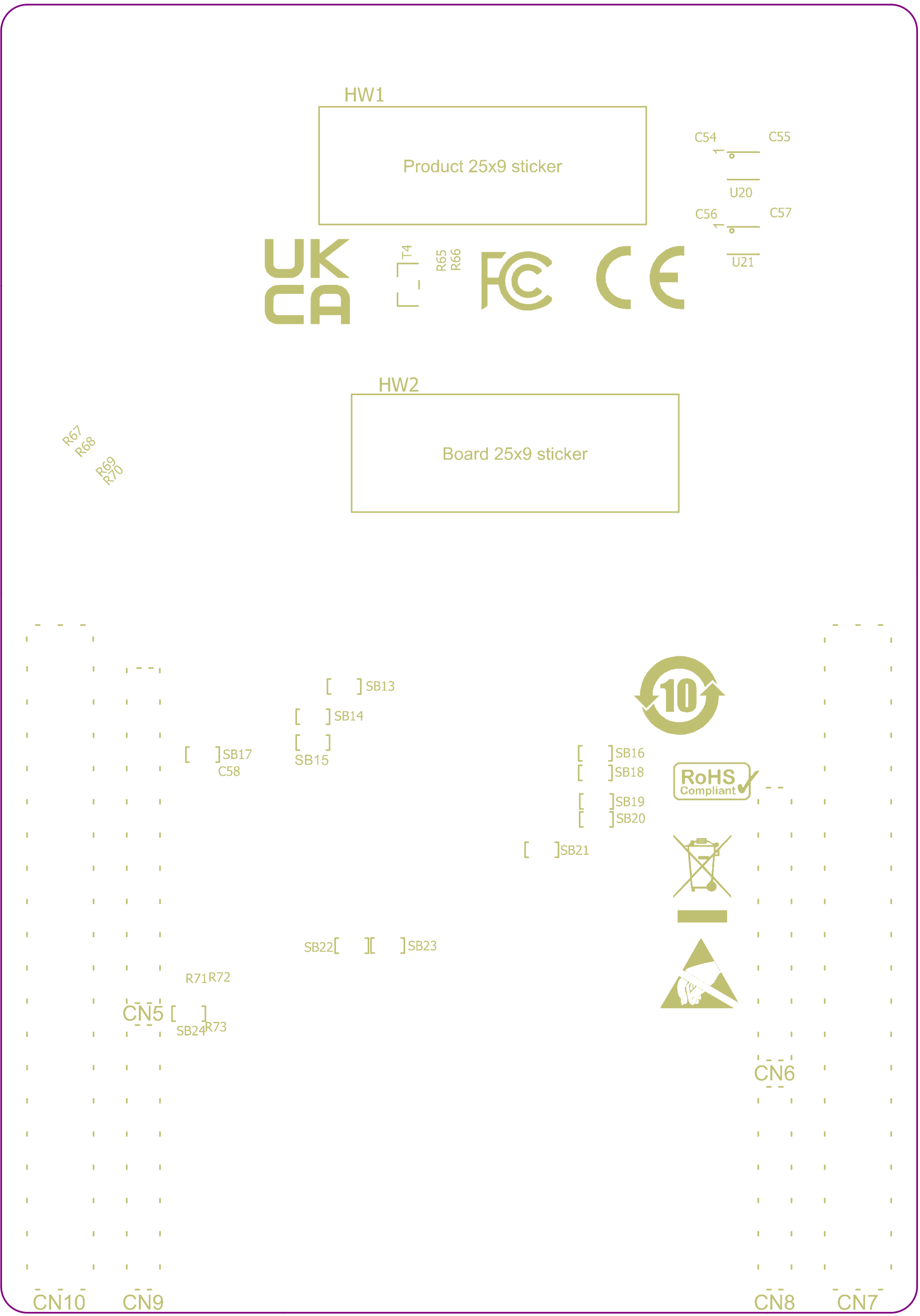
Ref: MB1933


Rev: C



















Project: STM32U083C-DK		
Layer: Bottom Solder	Gerber:.GBS	
Variant: U083C	Ref: MB1933	
Date: 26-SEP-2023	Rev: C	

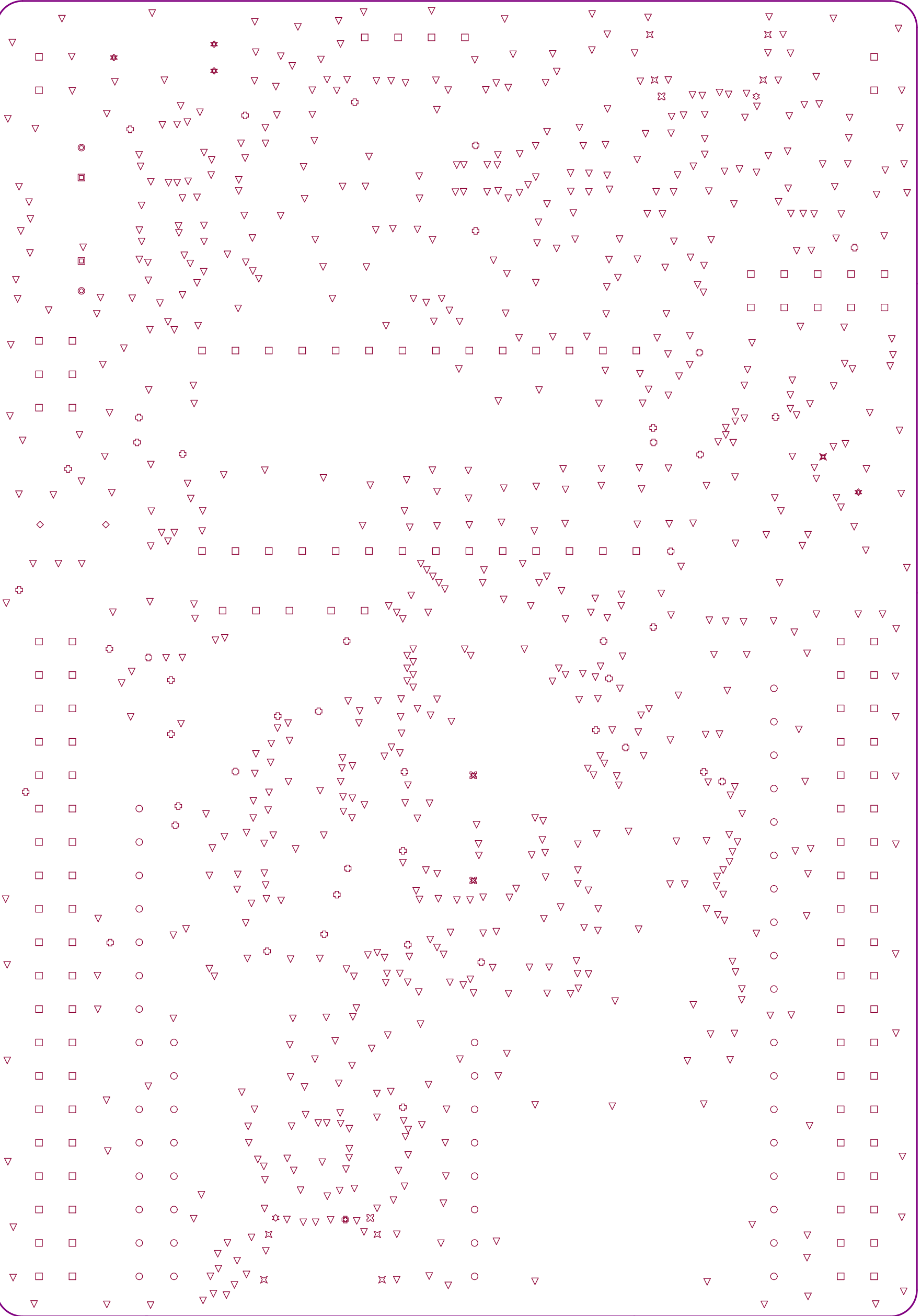


Project: STM32U083C-DK		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: U083C	Ref: MB1933	
Date: 26-SEP-2023	Rev: C	



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Hole Length	Routed Path Length
	1	11.81mil (0.30mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v50h30m0mx0	-	-
	1	31.50mil (0.80mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn80m85p-1	-	-
	2	25.59mil (0.65mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn65m5	-	-
	2	25.59mil (0.65mm)	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	c0hn65_95m5	37.40mil (0.95mm)	11.81mil (0.30mm)
	2	31.50mil (0.80mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)	-	-
	2	38.19mil (0.97mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn97m102	-	-
	2	46.85mil (1.19mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn119m124	-	-
	2	59.06mil (1.50mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn150m155	-	-
	4	43.31mil (1.10mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)	-	-
	8	19.69mil (0.50mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r140_80h50_110r100m145_85	43.31mil (1.10mm)	23.62mil (0.60mm)
	45	15.75mil (0.40mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v70h40m0mx0	-	-
	48	43.31mil (1.10mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)	-	-
	137	39.37mil (1.00mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)	-	-
	740	9.84mil (0.25mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v45h25m0mx0	-	-
	996 Total									

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



PCB SPECIFICATIONS :

- A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140
- B. MATERIAL FAMILY :

N/A
- C. SOLDERMASK COLOR :

☐ GREEN

☒ BLUE

☐ RED

☐ BLACK
- D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

☐ Blue ink PANTONE 2955
- E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER
- ☒ F. IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)
- G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.


PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.
- ☒ H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.015mm	3.5	
1	Top Layer		0.035mm		
	Dielectric 1	FR-4	0.200mm	4.2	
2	GND		0.035mm		
	Dielectric 3		1.000mm	4.2	
3	POWER		0.035mm		
	Dielectric 2		0.200mm	4.2	
4	Bottom Layer		0.035mm		
	Bottom Solder	Solder Resist	0.015mm	3.5	
	Bottom Overlay				

PCB : TYPE 3
ASPECT-RATIO, AXE Z : 6:1 to 8:1 LEVEL "B"
MINIMUM PARAMETERS
DEFAULT TRACKS : 0.14mm GAPS : 0.127mm

IMPEDANCE TABLE USB HS STLINK					
LAYER	TRACE (mm)	SPACING (mm)	IMPEDANCE (Single ended)	IMPEDANCE (Differential)	TOL.
TOP	0.27	0.2	n/a	90 ohm	+/- 15%

Project: STM32U083C-DK		
Layer: Drill Drawing	Gerber: .DRL	
Variant: U083C	Ref: MB1933	
Date: 26-SEP-2023	Rev: C	